

Product / Package Information	
Package	MSOP
Body Size	
Lead Count	8
Terminal Finish	100 Sn

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

### Materials Declaration

#### Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	1.10E-02	86.9	869100	43.90		438953
Thermosets	Epoxy & Phenol resin	Proprietary	1.62E-03	12.8	127800	6.45		64548
Other inorganic materials	Carbon black	1333-86-4	3.93E-05	0.3	3100	0.16		1566
Subtotal			1.27E-02	100.00	1000000	50.51		505067

#### Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	9.80 E-03	96.20	962000	38.25		382540
Copper & its alloys	Nickel	7440-02-0	2.99 E-04	3.00	30000	1.19		11930
Copper & its alloys	Silicon	7440-21-3	6.49 E-05	0.65	6500	0.26		2585
Copper & its alloys	Magnesium	7439-95-4	1.50 E-05	0.15	1500	0.06		596
Subtotal			9.98 E-03	100.00	1000000	39.77		397650

#### Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.01 E-04	100.0	1000000	0.40		4017

#### External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	6.54 E-04	100.0	1000000	2.61		26057

#### Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	3.06 E-04	99.0	990000	1.221		12205
Precious metals	Palladium	7440-05-3	3.09 E-06	1.0	10000	0.012		123
Subtotal			3.09 E-04	100.0	1000000	1.23		12328

#### Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	9.98 E-04	100.0	1000000	3.98		39769

#### Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.92 E-04	77.00	770000	1.16		11636
Other organic materials	Acrylic resin	Proprietary	2.66 E-05	7.00	70000	0.11		1059
Other organic materials	Acrylate	Proprietary	2.09 E-05	5.50	55000	0.08		831
Other organic materials	Polybutadiene derivative	Proprietary	1.71 E-05	4.50	45000	0.07		680
Thermoset	Epoxy resin	Proprietary	9.48 E-06	2.50	25000	0.04		378
Other organic materials	Butadiene Copolymer	Proprietary	5.69 E-06	1.50	15000	0.02		227
Others	Additive	Proprietary	5.69 E-06	1.50	15000	0.02		227
Others	Peroxide	Proprietary	1.90 E-06	0.50	5000	0.008		76
Subtotal			3.79 E-04	100.0	1000000	1.51		15112

Package Totals	Weight (g)	Percentage (%)	PPM
	2.51 E-02	100	1000000

Control ID: MS010628CPKG3733

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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